

Session Title:	[Mo3I] Laser Cutting
Session Date:	August 5 (Mon.), 2024
Session Time:	15:15-16:45
Session Room:	Room I (118)
Session Chairs	TBA

[Mo3I-1] [Invited] 15:15-15:45

Underwater Laser Cutting for Decommissioning of Nuclear Power Plants using High Power Laser

Su Jin Lee, Ding Sig Shin, Jeong Suh, In Duck Park (Korea Inst. of Machinery & Materials, Korea), and Jong Do Kim (Korea Maritime and Ocean Univ., Korea)

[Mo3I-2] 15:45-16:00

The Study on Nanosecond Pulsed Laser Dicing Process of Full-Thickness Silicon Wafer

Yeongil Son and Joonghan Shin (Kongju Nat'l Univ., Korea)

[Mo3I-3] 16:00-16:15

60 mm Heterogeneous Metal Cutting of 1 kW Laser and Oxygen Hybrid Cutting

Hanjin Jo, Sion Kim, Geonhui Lee (Handong Global Univ., Korea), Duckbong Seo (Sun Engineering Inc., Korea), and Tae Jun Yu (Handong Global Univ., Korea)

[Mo3I-4] 16:15-16:30

Acousto-optic Material Differentiation During Water Jet Guided Laser Cutting by Applying a Neural Network

Roland Axel Richter (EMPA, Switzerland), Luca Disalvo (Synova SA, Switzerland), Toni Ivas, Vigneashwara Pandiyan (EMPA, Switzerland), Amédée Zryd (Synova SA, Switzerland), Patrik Hoffmann, and Sergey Shevchik (EMPA, Switzerland)

[Mo3I-5] 16:30-16:45

Comparison of Lithium-ion Battery Laser Cutting Characteristics

M. Seong, M. Park, H. Kim, and D. Lee (Kongju Nat'l Univ., Korea)